



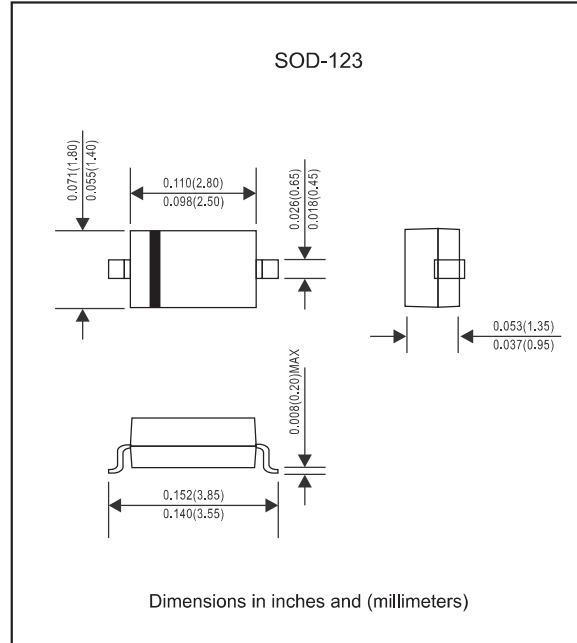
Features

- Low current rectification and high speed switching
- Extremely small surface mount type
- Low forward voltage drop
- Silicon epitaxial planar chip, metal silicon junction
- Lead-free parts meet RoHS requirements
- Halogen-free

Mechanical data

- Epoxy: UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-123
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any

Package outline



Maximum ratings (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

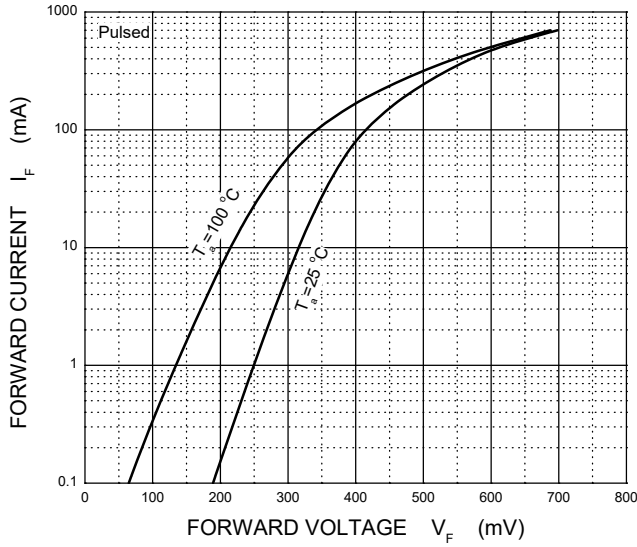
| Parameter | Conditions | Symbol | BAT48ZFILM | Unit |
|--|---------------------|---------------------------------|-------------|--------------------|
| Peak repetitive reverse voltage Working peak reverse voltage DC blocking voltage | | V_{RRM} V_{RWM} V_R | 40 | V |
| RMS reverse voltage | | $V_{R(RMS)}$ | 28 | V |
| Average rectified output current | | $I_{F(AV)}$ | 350 | mA |
| Non-repetitive peak forward surge current | @ $t=8.3\text{ms}$ | I_{FSM} | 2 | A |
| Total device dissipation | | P_D | 400 | mW |
| Thermal resistance | Junction to ambient | $R_{\theta JA}$ | 250 | $^\circ\text{C/W}$ |
| Operating junction temperature range | | T_J | -55 to +125 | $^\circ\text{C}$ |
| Storage temperature range | | T_{STG} | -55 to +150 | $^\circ\text{C}$ |

Electrical characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

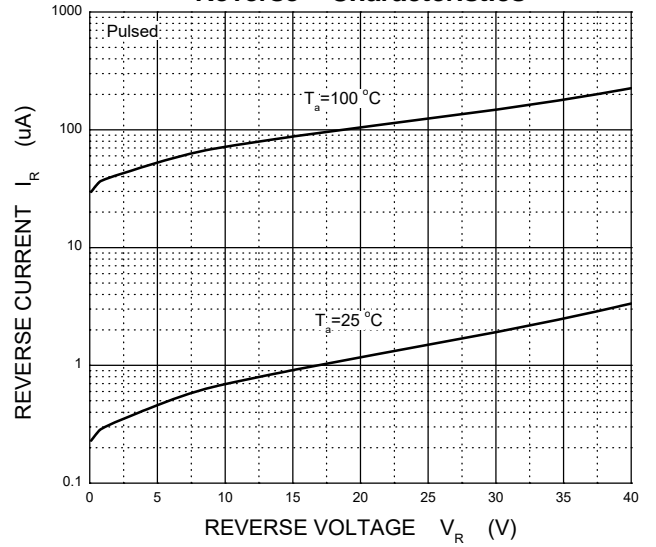
| Parameter | Conditions | Symbol | MIN. | TYP. | MAX. | Unit |
|------------------------------|---|-------------|------|------|--------------|---------------|
| Reverse breakdown voltage | $I_R=100\mu\text{A}$ | $V_{(BR)R}$ | 40 | | | V |
| Forward voltage | $I_F=20\text{mA}$ $I_F=200\text{mA}$ | VF | | | 0.37 0.60 | V |
| Reverse leakage current | $V_R=30\text{V}$ | I_R | | | 5.0 | μA |
| Typical junction capacitance | $V_R=0\text{V}$, $f=1.0\text{MHz}$ | C_J | | 50 | | pF |
| Reverse recover time | $I_F=I_R=200\text{mA}$, $I_{tr}=0.1 \times I_R$, $R_L=100\Omega$ | trr | | 10 | | nS |

Rating and characteristic curves

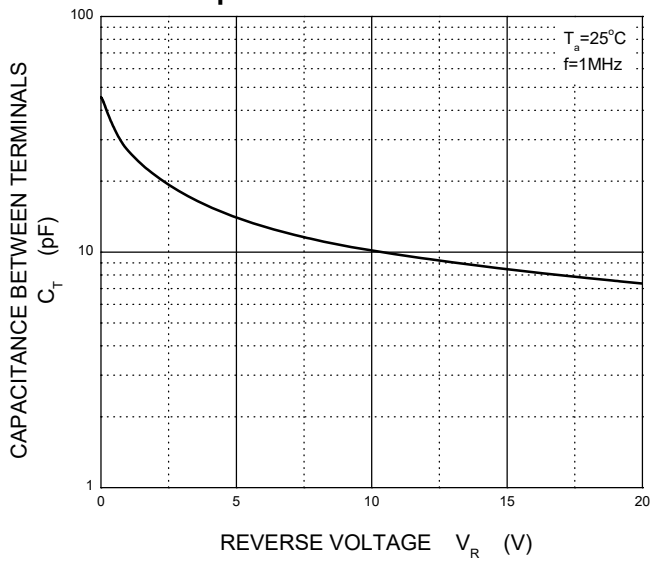
Forward Characteristics



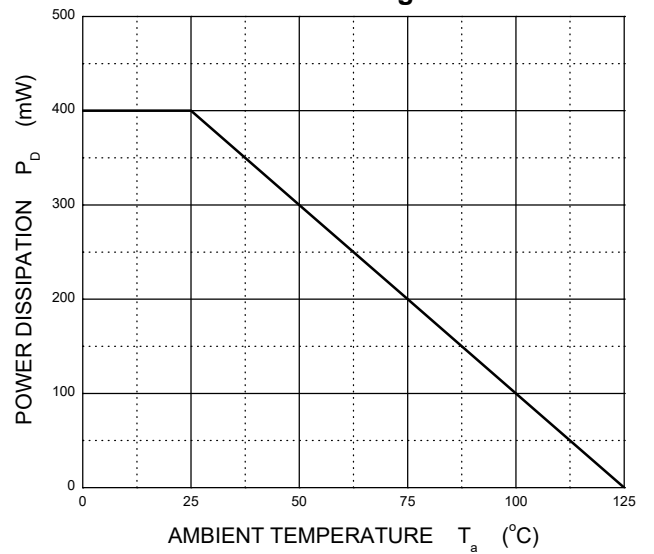
Reverse Characteristics





Capacitance Characteristics



Power Derating Curve



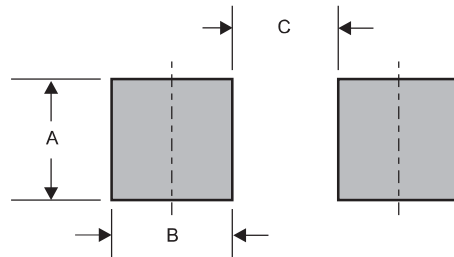
Pinning information

| Pin | Simplified outline | Symbol |
|----------------------------|---|---|
| Pin1 cathode Pin2 anode |  |  |

Marking

| Type number | Marking code |
|-------------|--------------|
| BAT48ZFILM | S4 |

Suggested solder pad layout



Dimensions in inches and (millimeters)

| PACKAGE | A | B | C |
|---------|--------------|--------------|--------------|
| SOD-123 | 0.048 (1.22) | 0.036 (0.91) | 0.093 (2.36) |